



景碩科技股份有限公司
Kinsus Interconnect Technology Corp.

Feb 2024



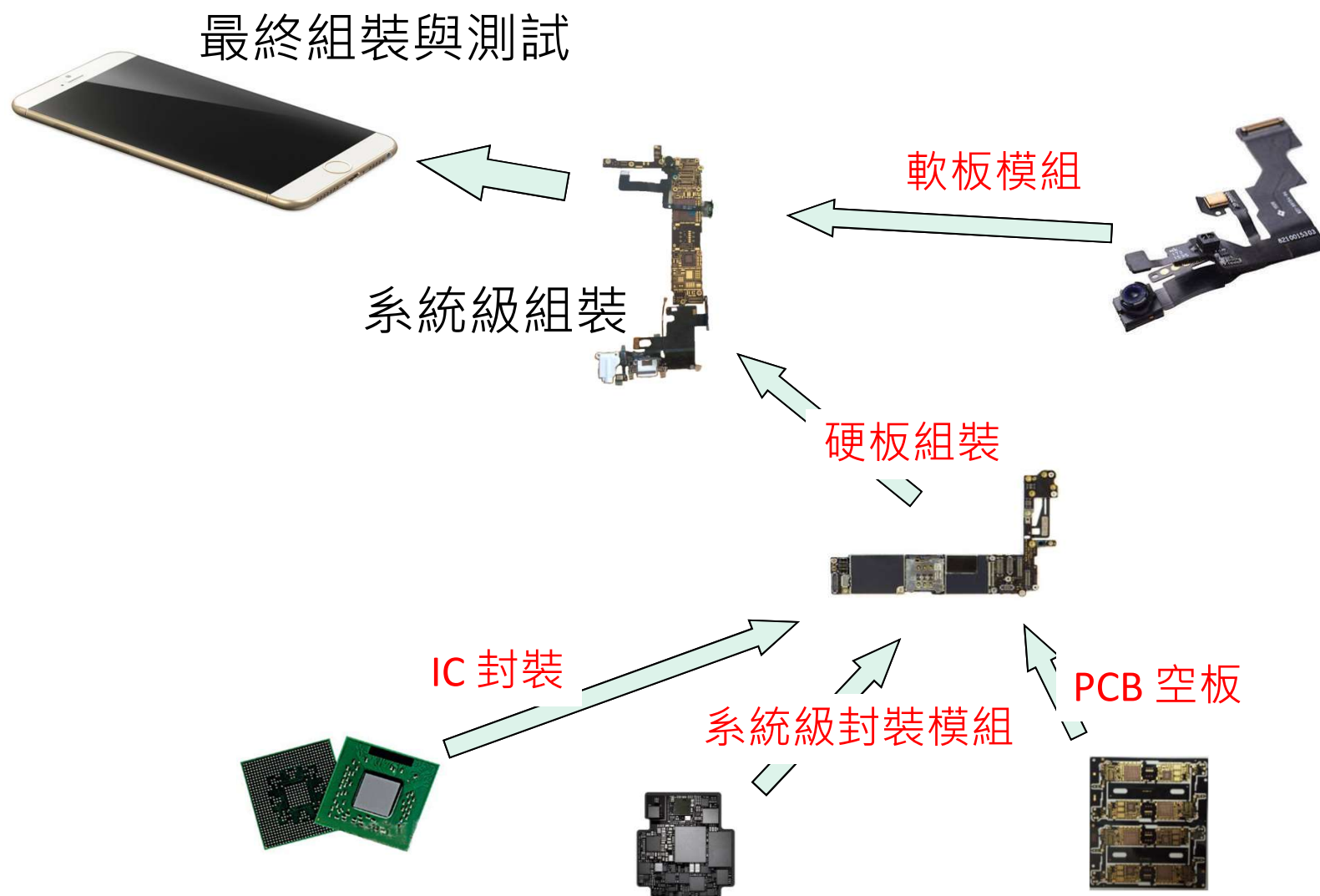


IC 封裝技術

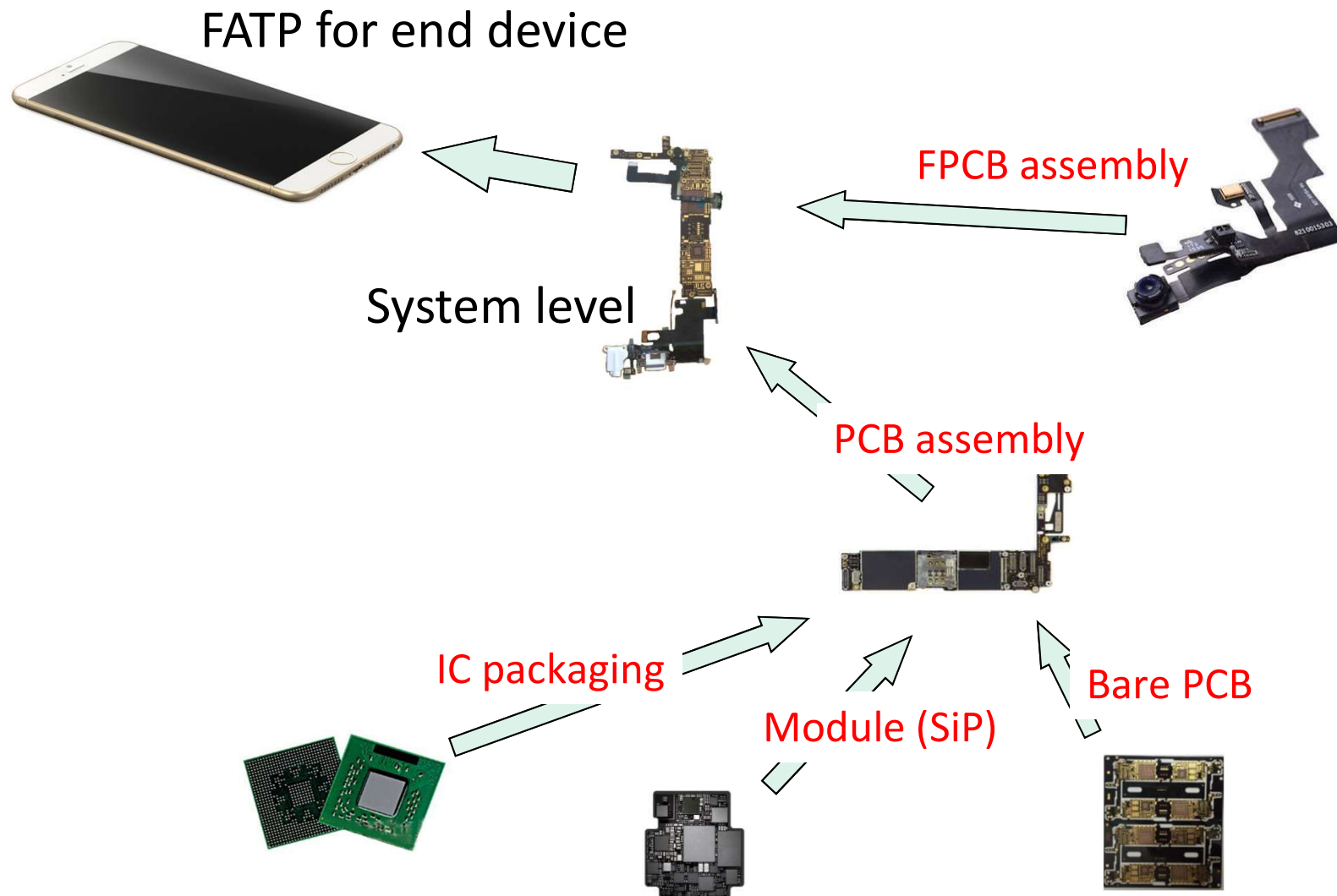
IC Packaging Technology



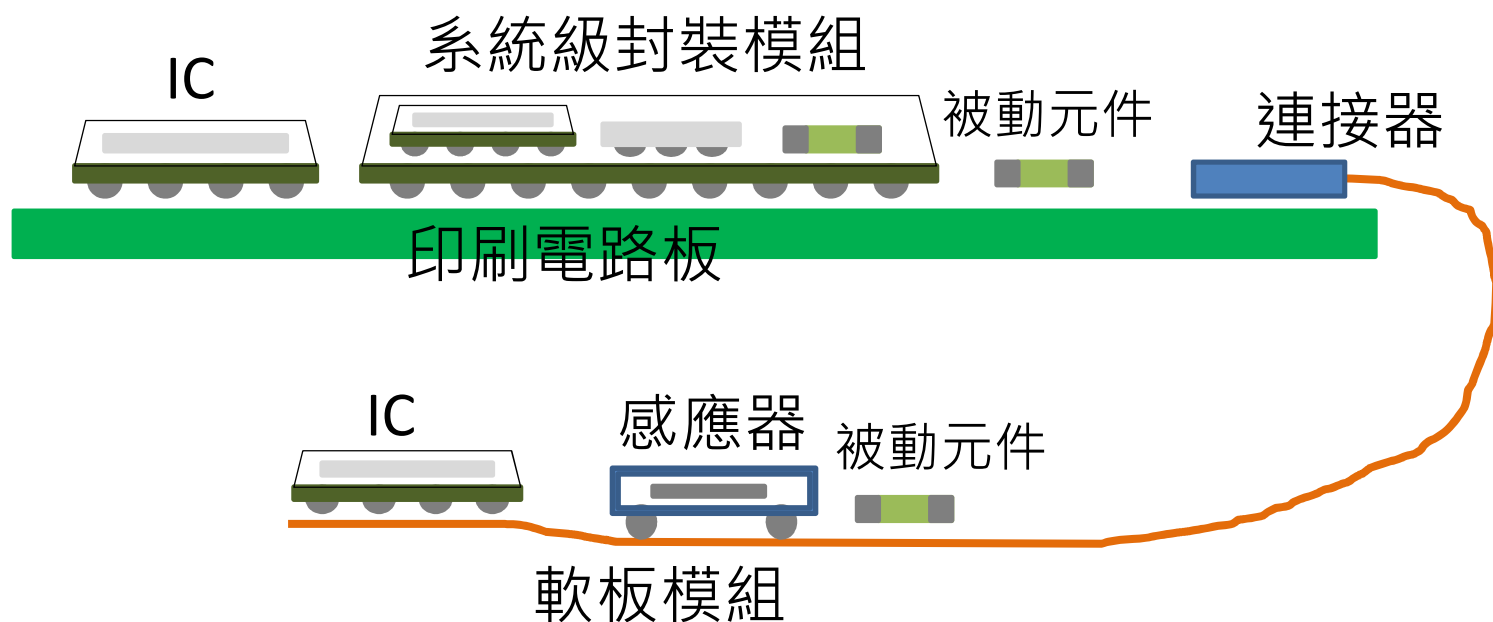
電子產品構裝的各個層次



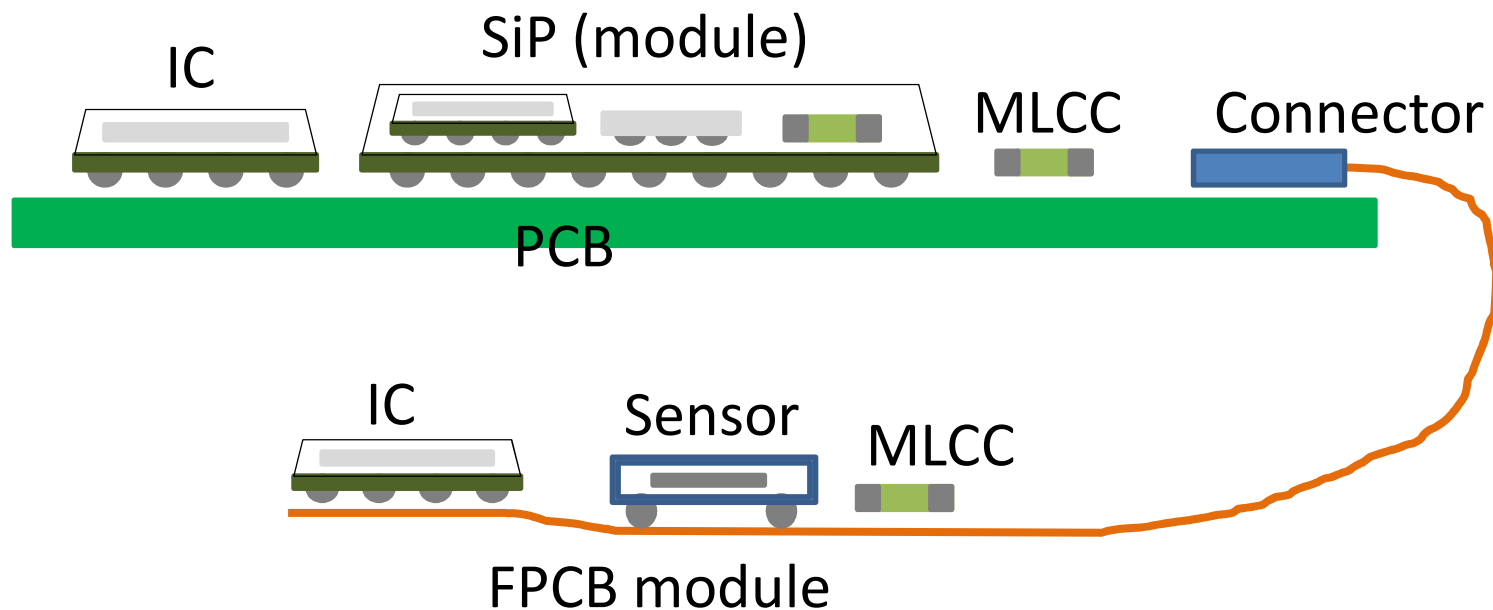
Levels of Assembly



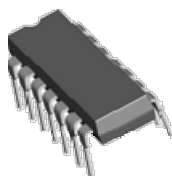
電子產品的組裝結構



Basic structure of electronic devices



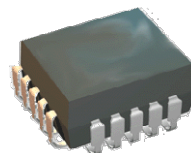
各種形式的IC 封裝



DIP



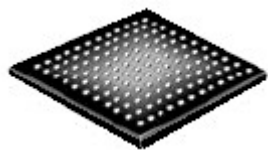
QFP



PLCC



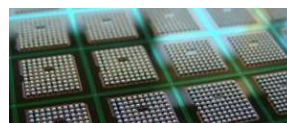
TSOP



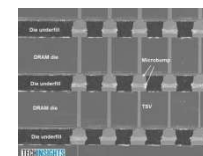
PBGA/
Flip-Chip BGA



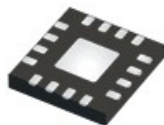
CSP



WLP



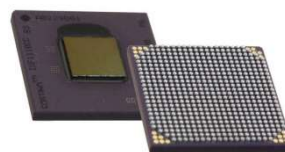
TSV



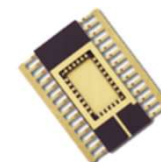
QFN



DFN



Ceramic BGA

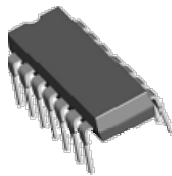


Ceramic chip

BGA 封裝 市場規模: 2023 年828 億顆, 產值 161億美元



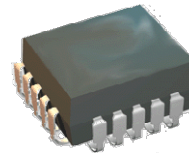
Different types of IC packaging



DIP



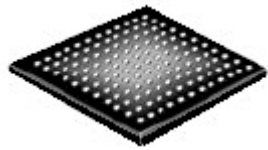
QFP



PLCC



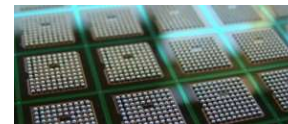
TSOP



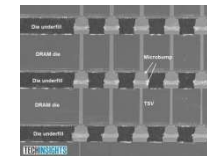
PBGA/
Flip-Chip BGA



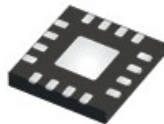
CSP



WLP



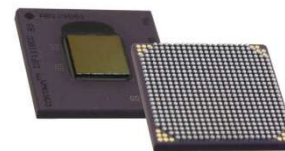
TSV



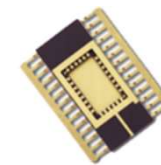
QFN



DFN



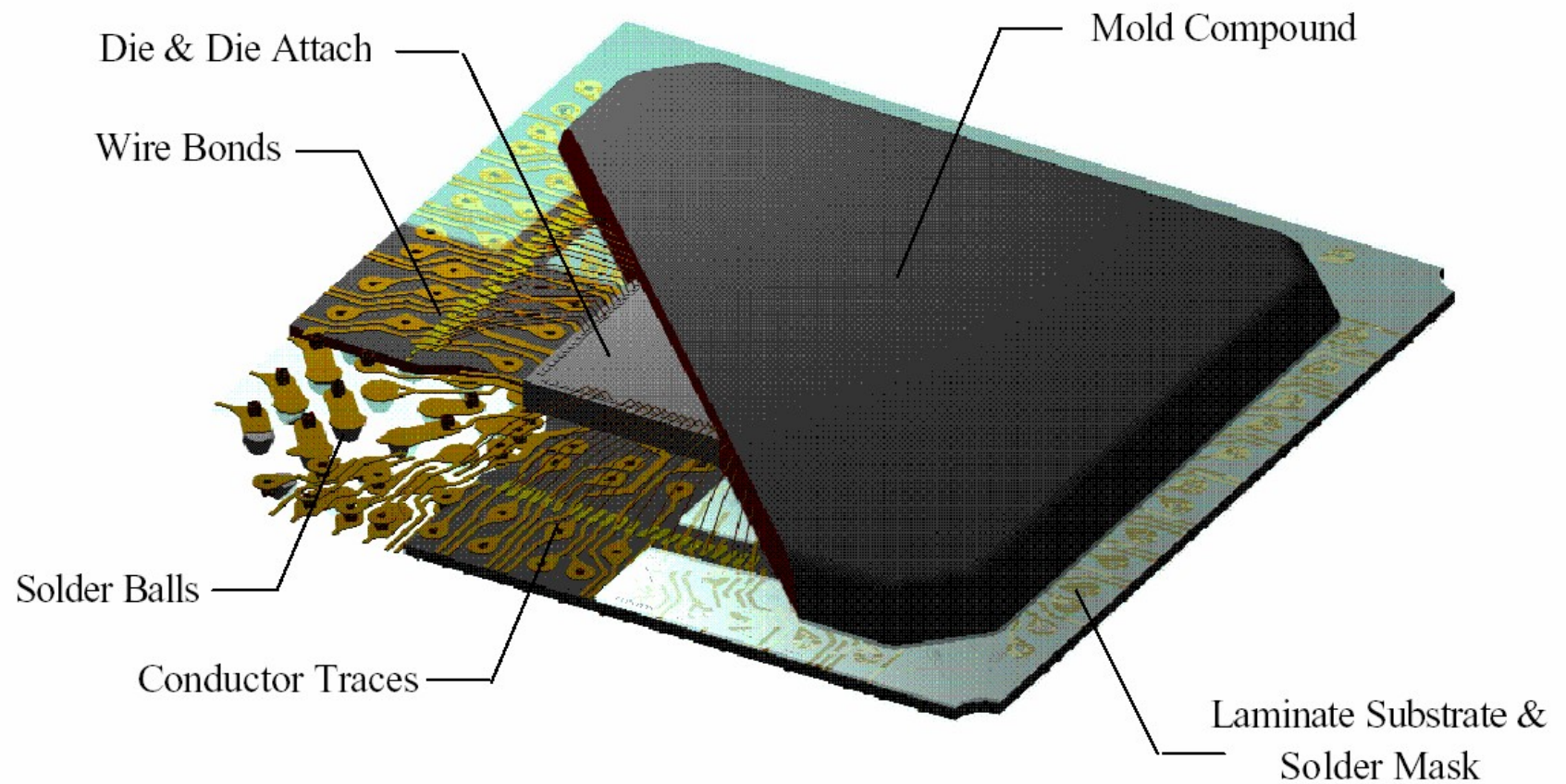
Ceramic BGA



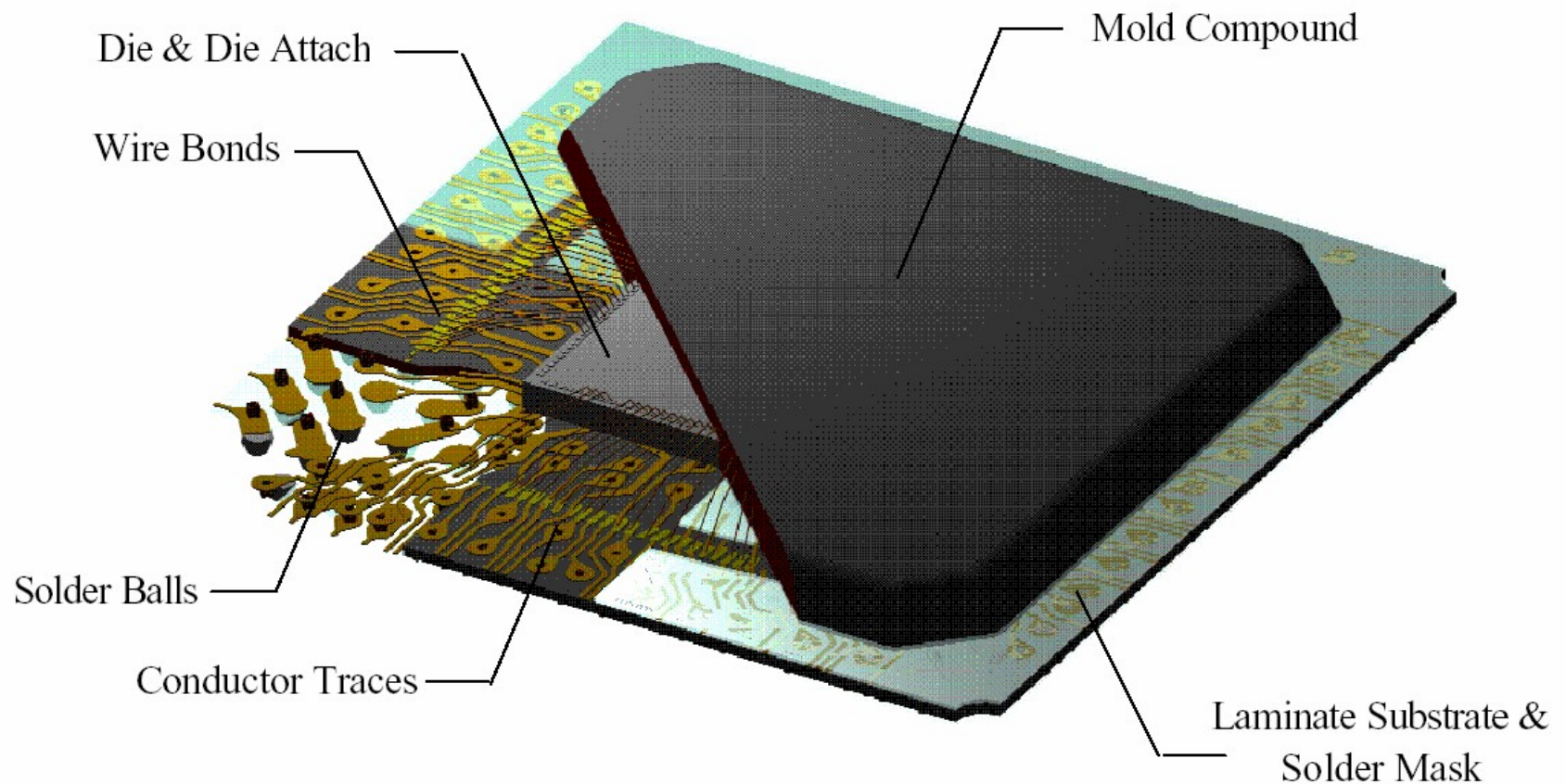
Ceramic chip

BGA Market size : 8 2 Billion units, 1 6 Billion U S \$ i n 2 0 2 3

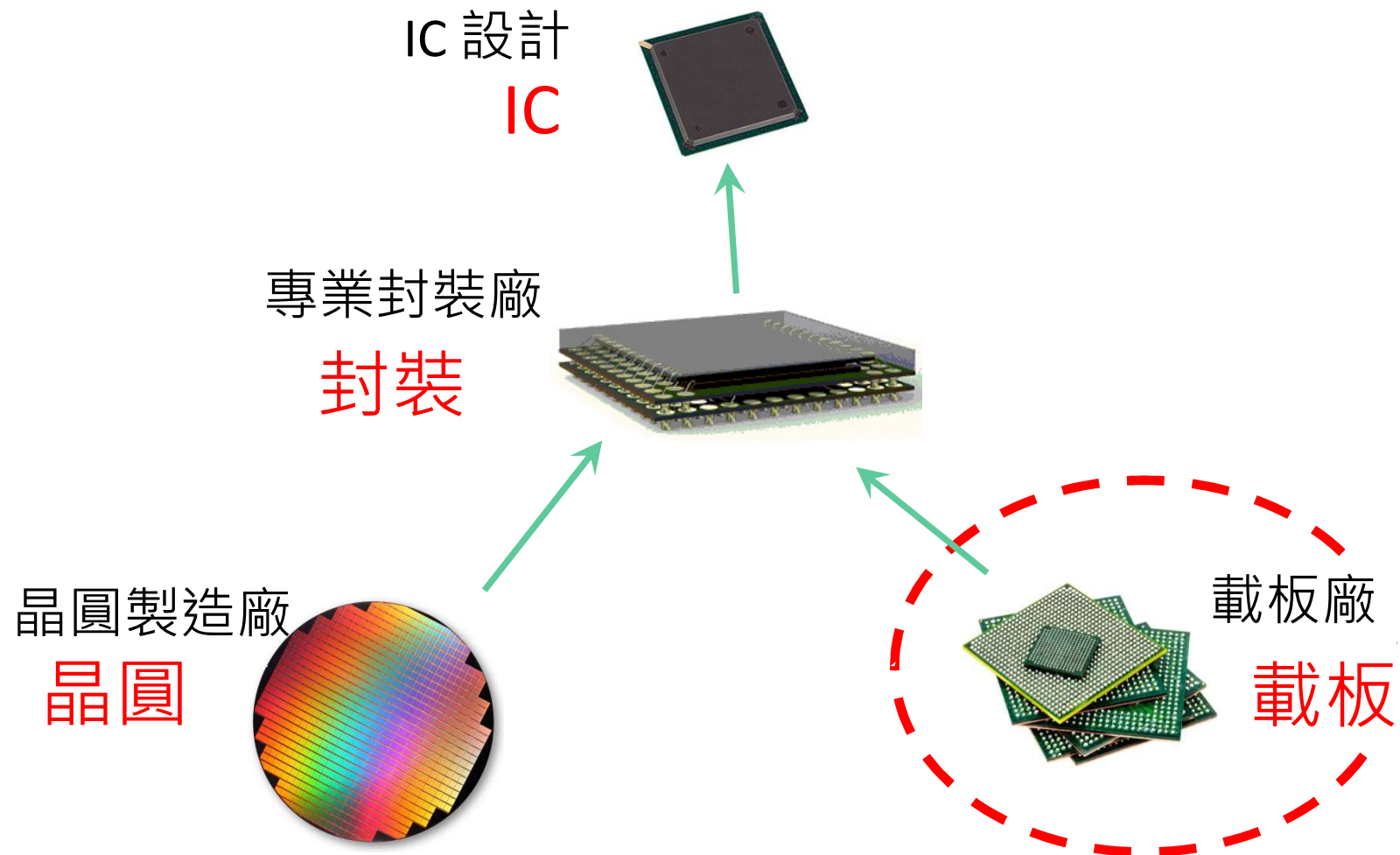




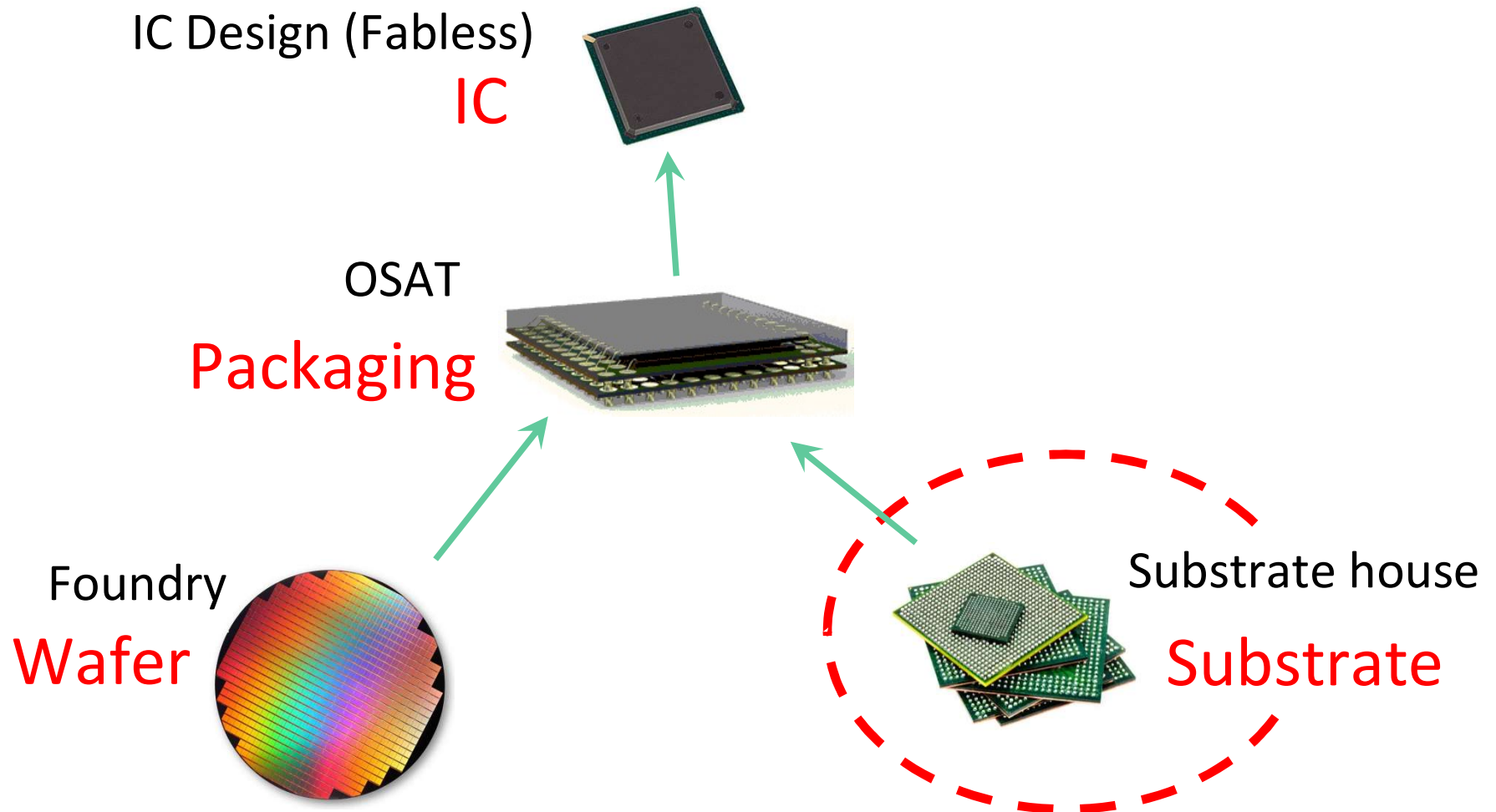
What Substrate Makers do?



IC 半導體上下游供應鏈關係



IC Manufacturing Supply Chain





About Kinsus



基本資料



- 公司成立 2000
台股上市掛牌 2004
- 資本額： 新台幣 45.68 億元
- 廠區： 總部
 - 新屋 / 台灣
 - 一廠 及 二廠
 - 五廠 及 六廠

Kinsus USA

 - Santa Clara / California

統碩科技

 - 蘇州 / 中國

晶碩光學

 - 桃園 / 台灣



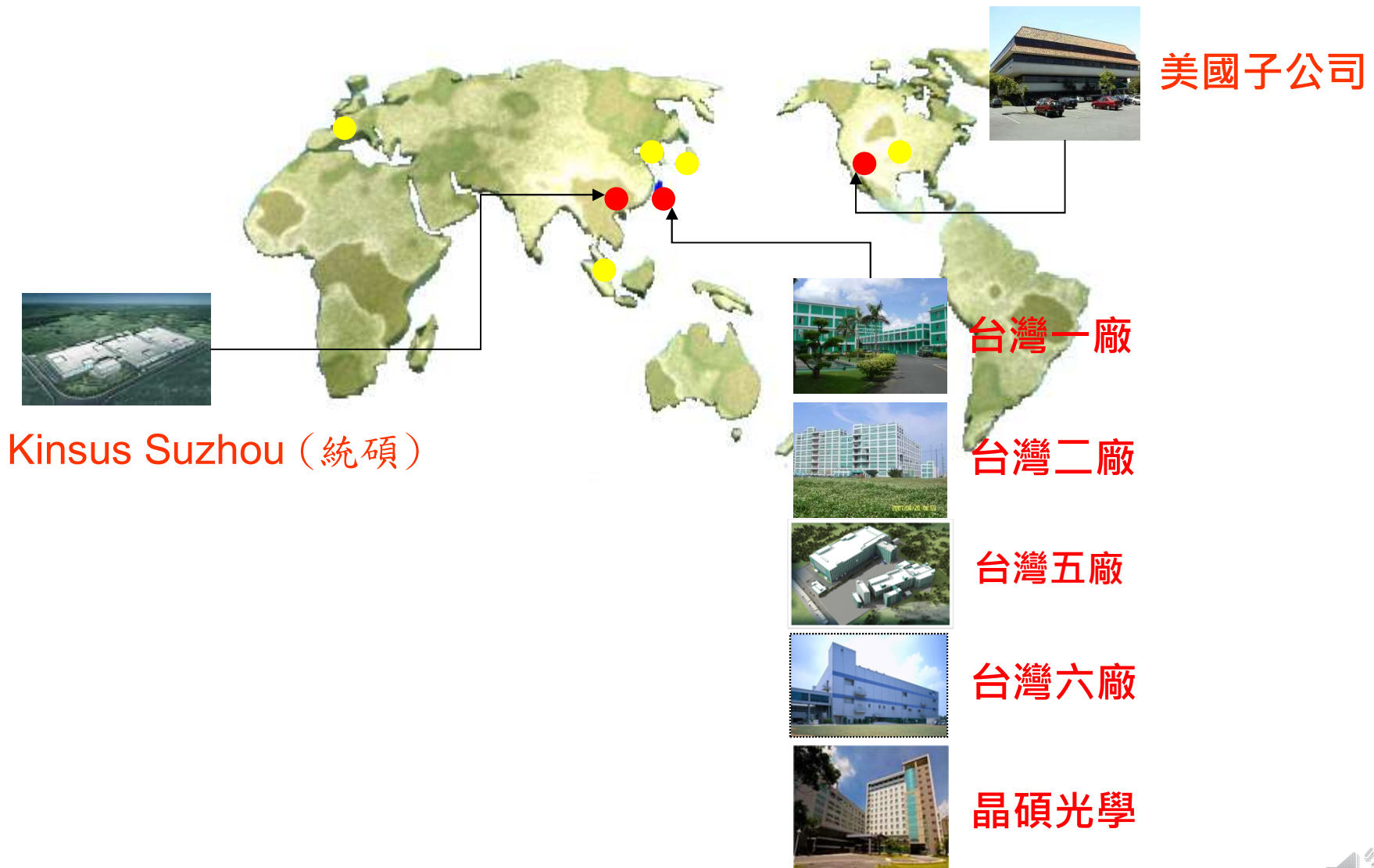
Basic Information



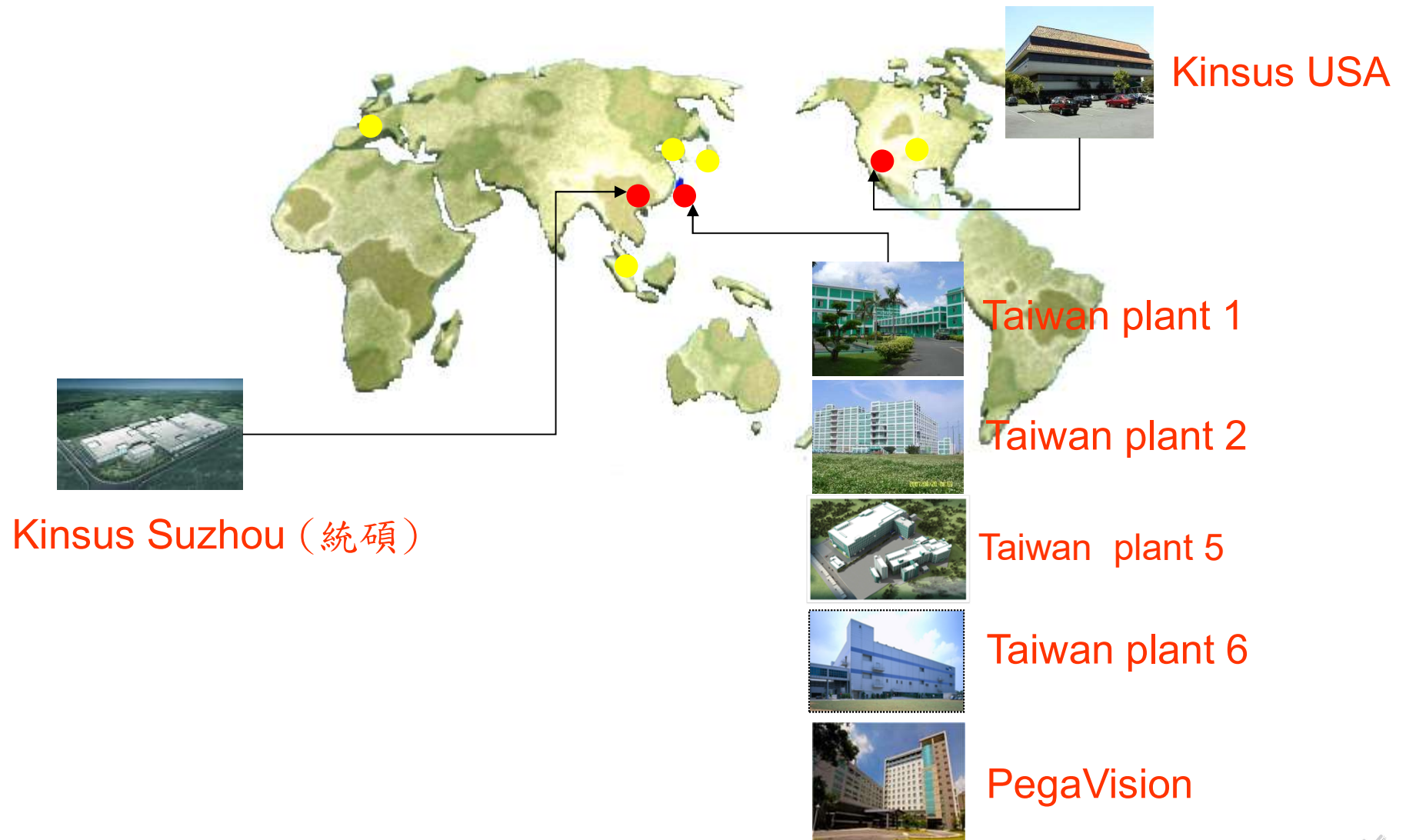
- Established in September 2000
IPO at TWSE in November 2004
- Capital : US\$ 147 Million (NT\$ 4.568 Billion)
- Campus :
 - Headquarters
 - Xin Wu / Taiwan
 - Plant 1 & 2
 - Plant 5 & 6
 - IC substrates
 - Kinsus USA
 - Santa Clara / California
 - Kinsus China
 - Suzhou / China
 - PegaVision
 - Taoyuan / Taiwan

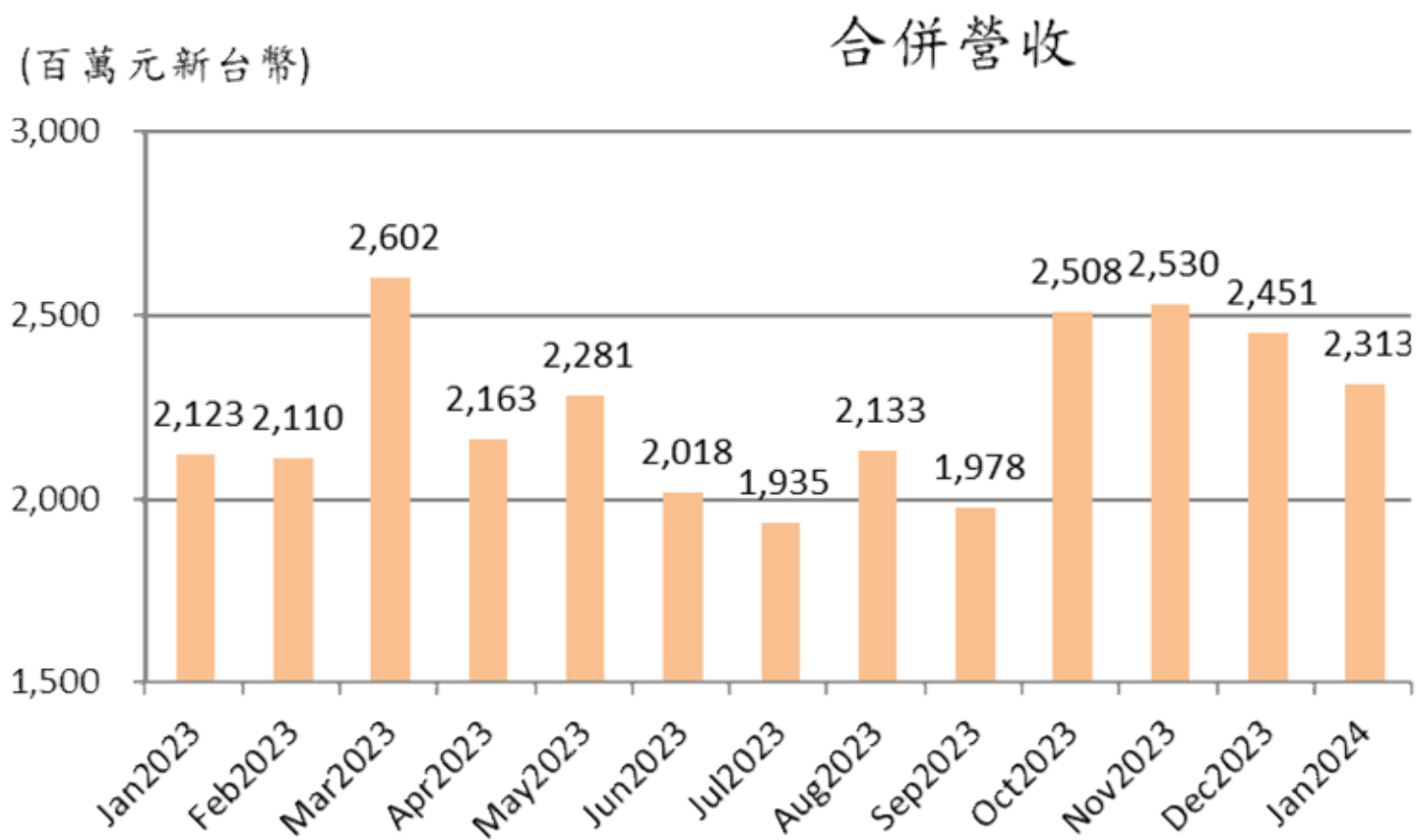


位置

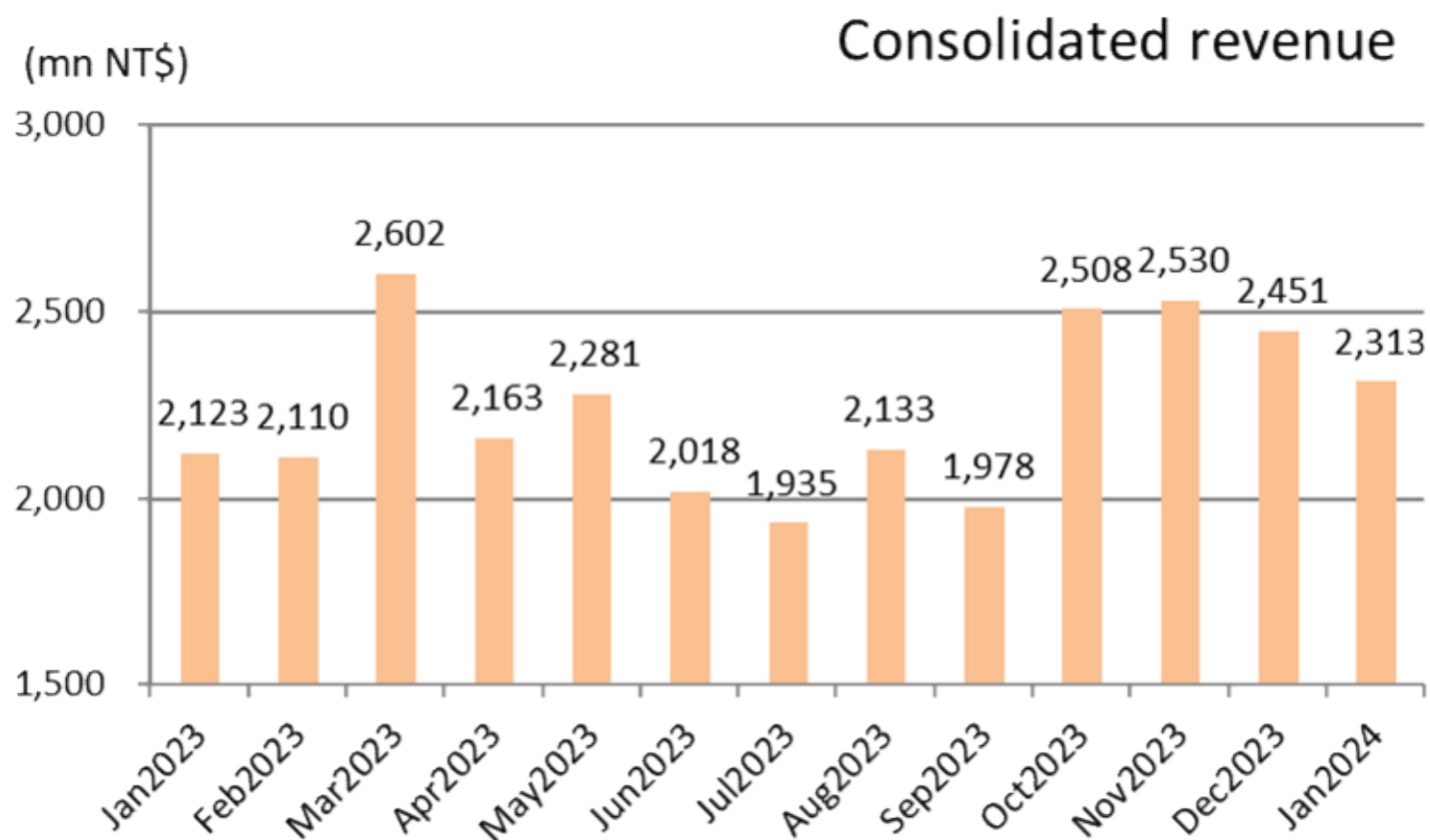


Locations

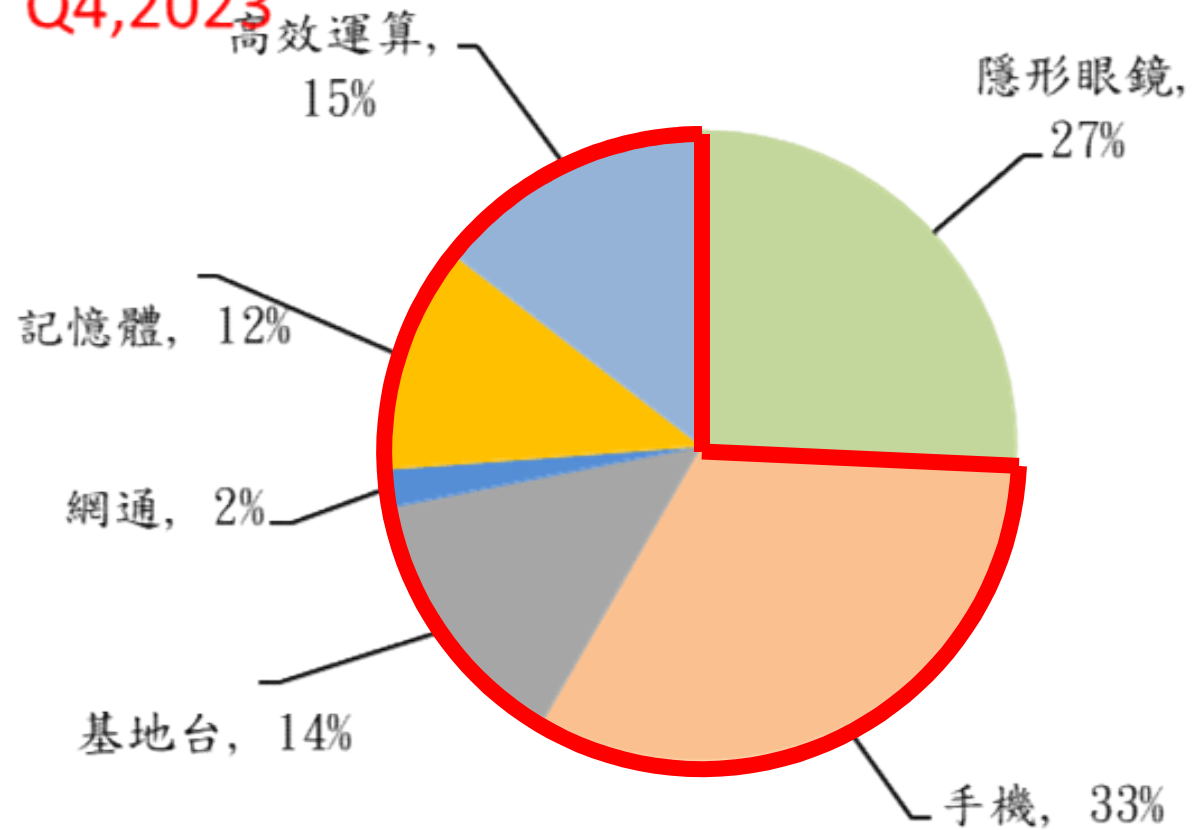




Monthly Revenue



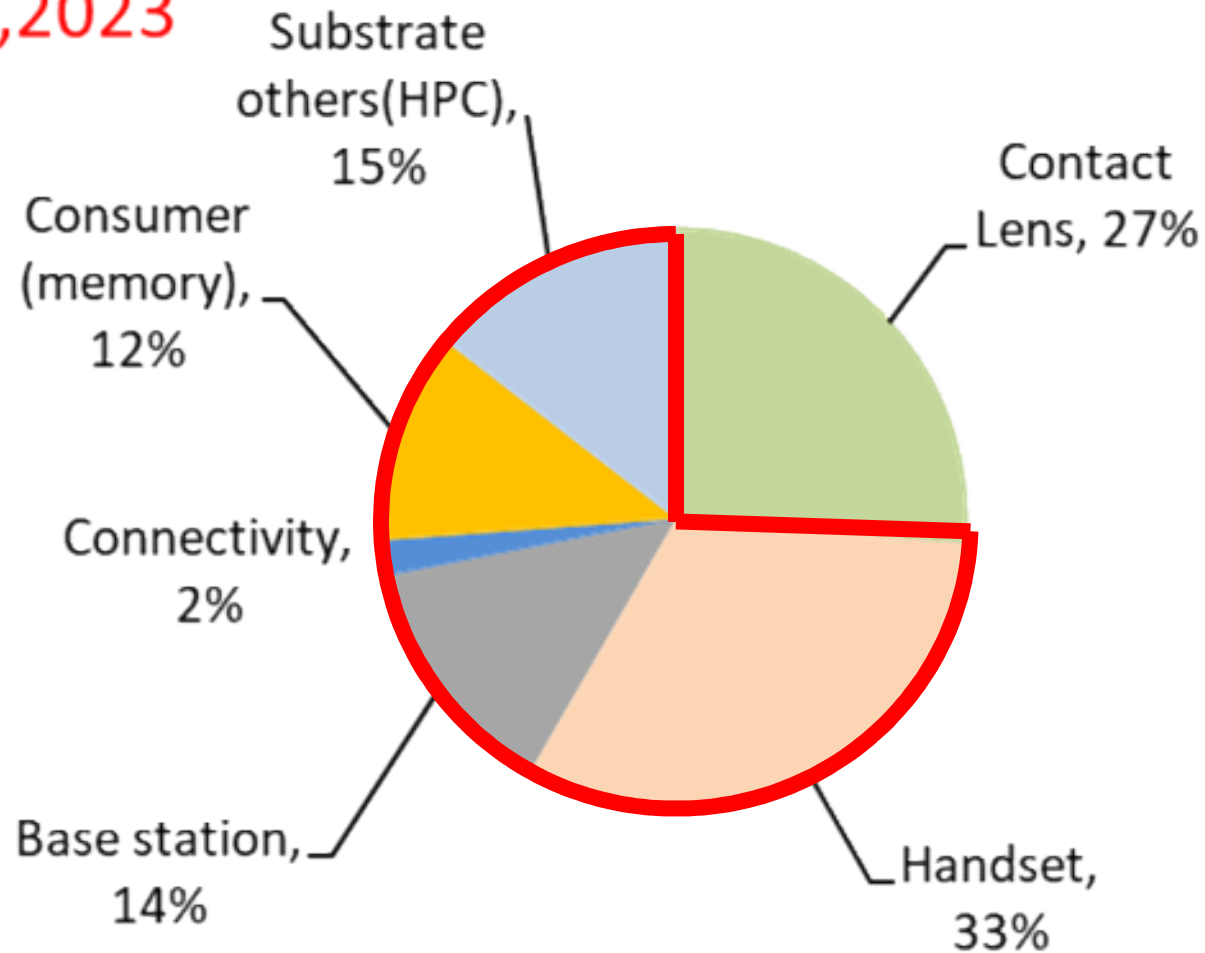
Q4, 2023



Product mix



Q4,2023





Thank you

